



Semiconductor Manufacturing International Corporation

Doc. No.: TD-LO18-DR-2006	Doc. Title: 0.18um Logic 1P6M Salicide 1.8/3.3v Current Density Design Rule	Doc.Rev: 0.1T	Tech Dev Rev: 0.1	Page No.:1/6
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Document Level: (For Engineering & Quality Document/工程暨品质文件专用)				
<input type="checkbox"/> Level 1 - Manual <input checked="" type="checkbox"/> Level 2 – Procedure/SPEC/Report <input type="checkbox"/> Level 3 - Operation Instruction				
Security Level:				
<input type="checkbox"/> Security 1 - SMIC Confidential <input checked="" type="checkbox"/> Security 2 - SMIC Restricted <input type="checkbox"/> Security 3 - SMIC Internal				
Document Change History				
Doc. Rev.	Tech Dev. Rev.	Effective Date	Author	Change Description
0T		2002-12-16	Brian Zhang	Initiate
0.1T	0.1	2003-06-10	JianHua_Ju	Add Technology Develop Revision:0.1

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1. Title:
0.18um Logic 1P6M Salicide 1.8/3.3v Current Density Design Rules
2. Purpose:
EM Design Guideline for 0.18um Logic Process
3. Scope:
All SMIC Fabs
4. Nomenclature: NA
5. Reference: NA
6. Responsibility: Technology Development Center
7. Subject Content: Unit: um

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0.18 μ m LOGIC 1P6M Salicide 1.8/3.3V

Current Density Design Rules

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CDR: Current Density Rule

RULE NO. DESCRIPTION

Rule

Metal Line

CDR.1	Jmax of M1 line at 110°C	1.0mA/um
CDR.2	Jmax of M2 line at 110°C	1.0mA/um
CDR.3	Jmax of M3 line at 110°C	1.0mA/um
CDR.4	Jmax of M4 line at 110°C	1.0mA/um
CDR.5	Jmax of M5 line at 110°C	1.0mA/um
CDR.6	Jmax of M6 line at 110°C	1.6mA/um

Contact and Via

CDR.7	Jmax per Contact at 110°C	0.53mA/cont
CDR.8	Jmax per V1 at 110°C	0.28mA/Via
CDR.9	Jmax per V2 at 110°C	0.28mA/Via
CDR.10	Jmax per V3 at 110°C	0.28mA/Via
CDR.11	Jmax per V4 at 110°C	0.28mA/Via
CDR.12	Jmax per V5 at 110°C	0.706mA/um

Stack Contact/Vias

CDR.13	Jmax per stacked V1/V2 at 110°C	0.28mA/Via
CDR.14	Jmax per stacked V2/V3 at 110°C	0.28mA/Via
CDR.15	Jmax per stacked V1/V2/V3 at 110°C	0.28mA/Via

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CDR.16	Jmax per stacked V3/V4 at 110°C	0.28mA/Via
CDR.17	Jmax per stacked V2/V3//V4 at 110°C	0.28mA/Via
CDR.18	Jmax per stacked V1/V2/V3/V4 at 110°C	0.28mA/Via
CDR.19	Jmax per stacked V4/V5 at 110°C	0.28mA/Via
CDR.20	Jmax per stacked V3/V4/V5 at 110°C	0.28mA/Via
CDR.21	Jmax per stacked V2/V3/V4/V5 at 110°C	0.28mA/Via
CDR.22	Jmax per stacked V1/V2/V3/V4/V5 at 110°C	0.28mA/Via
CDR.23	Jmax per stacked CT/V1 at 110°C	0.28mA/Via
CDR.24	Jmax per stacked CT/V1/V2 at 110°C	0.28mA/Via
CDR.25	Jmax per stacked CT/V1/V2/V3 at 110°C	0.28mA/Via
CDR.26	Jmax per stacked CT/V1/V2/V3/V4 at 110°C	0.28mA/Via
CDR.27	Jmax per stacked CT/V1/V2/V3/V4/V5 at 110°C	0.28mA/Via

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Notice:

Jmax is maximum DC current allowed per um of metal line width or per via or per contact. The number is based on 0.1% point of measurement data at 20% resistance increase after 10 years continuous operation.

Use the following table to convert Jmax from 110°C to another temperature.

Jmax transformation rate							
Temp.	70 °C	85 °C	100 °C	110 °C	125 °C	150 °C	175 °C
Jmax transformation rate from 110 °C	3.443	2.097	1.329	1	0.6707	0.3670	0.2148

Example: Jmax at 85°C = 2.097 * Jmax at 110°C = 2.097* 1mA/um = 2.097 mA/um for M1 to M6.

8. Attachment: NA

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